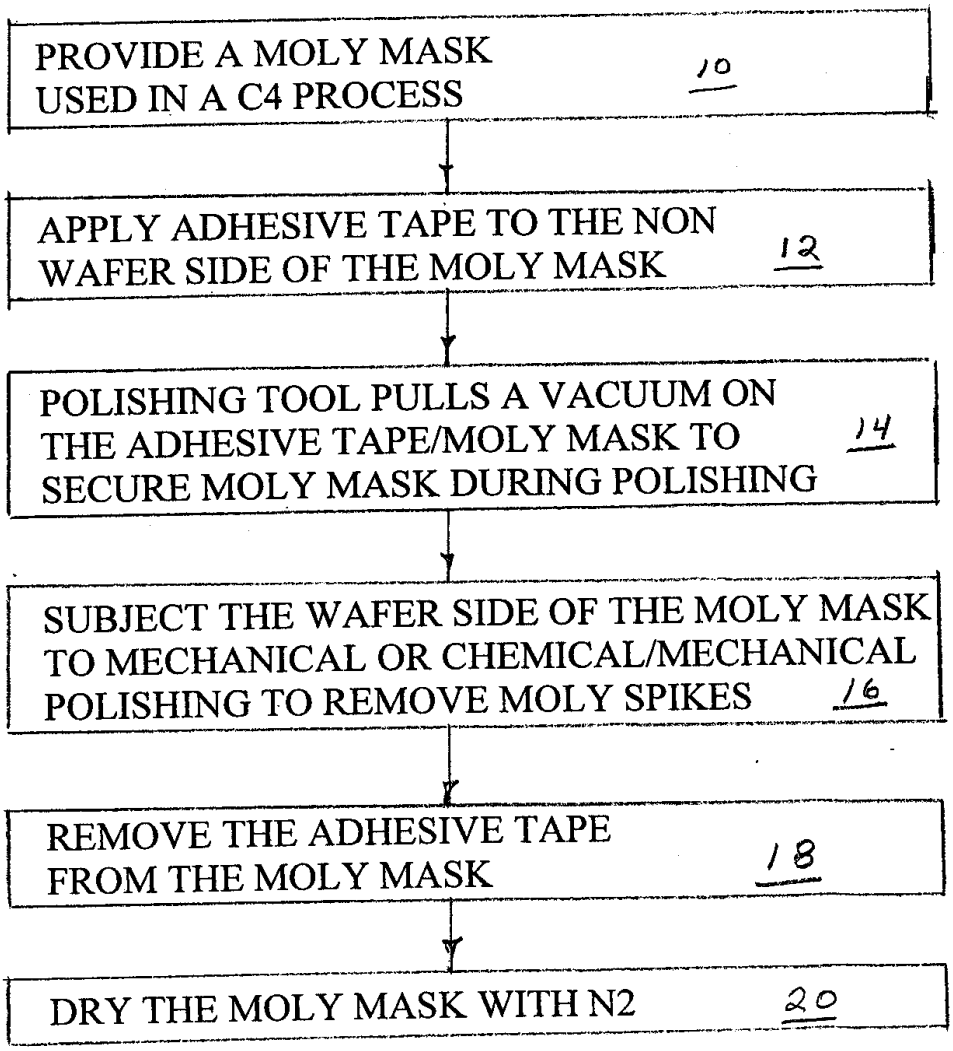
PROVIDE A MOLY MASK USED IN A C4 PROCESS 10
APPLY ADHESIVE TAPE TO THE NON WAFER SIDE OF THE MOLY MASK 12
POLISHING TOOL PULLS A VACUUM ON THE ADHESIVE TAPE/MOLY MASK TO SECURE MOLY MASK DURING POLISHING 14
SUBJECT THE WAFER SIDE OF THE MOLY MASK TO MECHANICAL OR CHEMICAL/MECHANICAL POLISHING TO REMOVE MOLY SPIKES 16
REMOVE THE ADHESIVE TAPE FROM THE MOLY MASK 18
DRY THE MOLY MASK WITH N2 20

FIGURE 1